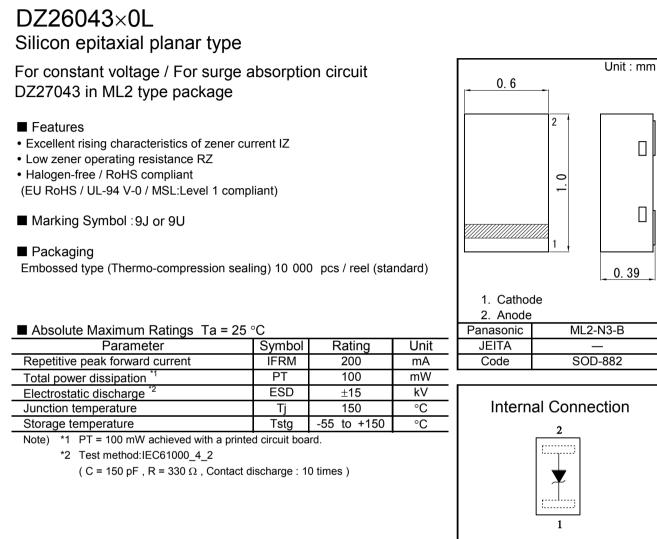


Zener Diode DZ26043×0L



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage *1, *2	VZ	IZ = 5 mA	4.09		4.52	V
Zener operating resistance	RZ	IZ = 5 mA			130	Ω
Reverse current	IR	VR = 1.0 V			10	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		-0.9		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

3. *1 The temperature must be controlled 25 °C for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25 °C)

*2 VZ guaranteed 20 ms after current flow.

*3 Tj = 25 °C to 150 °C

Rank classification

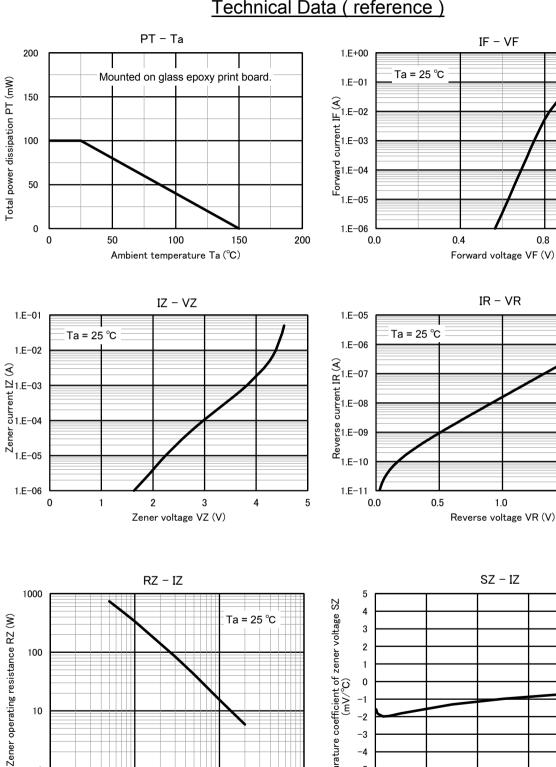
Code	М			0			
Rank	М			No-rank			
VZ	4.18	to	4.40	4.09	to	4.52	
Marking symbol		9U			9J		

Panasonic

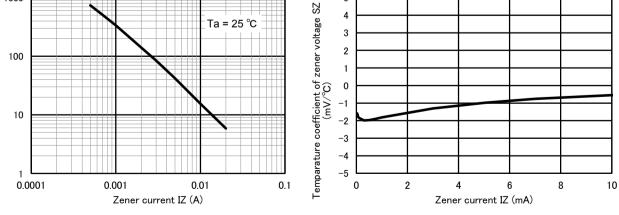
Zener Diode DZ26043×0L

1.2

2.0



Technical Data (reference)



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1.5

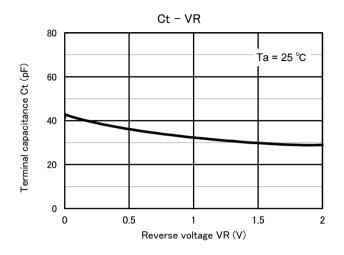
Established : 2013-04-03 Revised : 2017-01-10

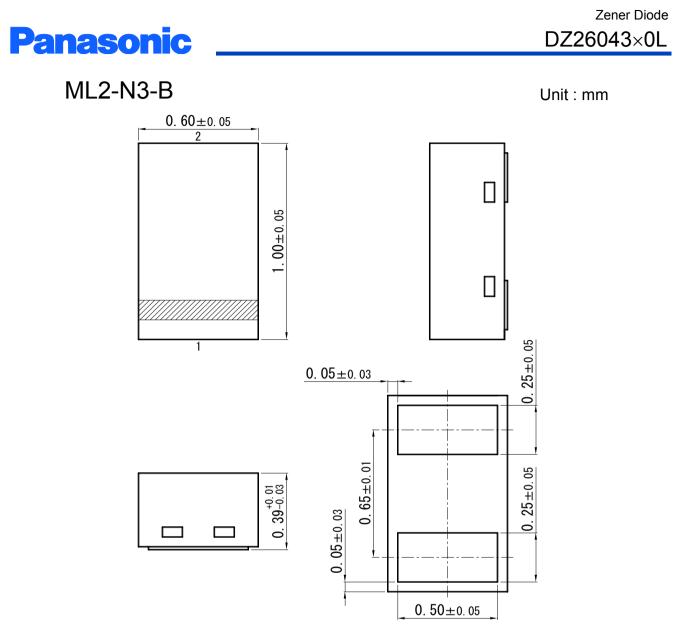
Doc No. TT4-EA-14586 Revision. 3



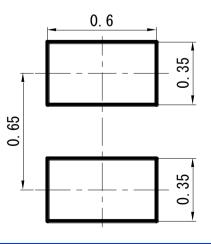
Zener Diode DZ26043×0L

Technical Data (reference)





■ Land Pattern (Reference) (Unit : mm)



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Established : 2013-04-03 Revised : 2017-01-10

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